





HIGH ISOLATION SPDT NON-REFLECTIVE SWITCH, DC - 4 GHz

Typical Applications

The HMC349AMS8G / 349AMS8GE is ideal for:

- Basestation Infrastructure
- MMDS & 3.5 GHz WLL
- CATV/CMTS
- Test Instrumentation

Features

High Isolation: 70 dB @ 1 GHz

57 dB @ 2 GHz

Single Positive Control: 0/+5V

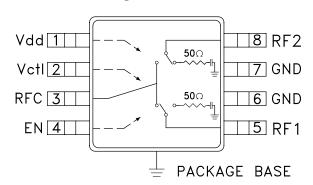
+52 dBm Input IP3

Non-Reflective Design

All Off State

Ultra Small MS8G SMT Package: 14.8 mm²

Functional Diagram



General Description

The HMC349AMS8G & HMC349AMS8GE are high isolation non-reflective DC to 4 GHz GaAs MESFET SPDT switches in low cost 8 lead MSOP8G surface mount packages with exposed ground paddles. The switch is ideal for cellular/PCS/3G basestation applications yielding 50 to 60 dB isolation, low 0.8 dB insertion loss and +52 dBm input IP3. Power handling is excellent up through the 3.5 GHz WLL band with the switch offering a P1dB compression point of +34 dBm. On-chip circuitry allows a single positive voltage control of 0/+5 Volts at very low DC currents. An enable input (EN) set to logic high will put the switch in an "all off" state.

Electrical Specifications, $T_{\Delta} = +25^{\circ}$ C, Vctl = 0/+5 Vdc, Vdd = +5 Vdc, 50 Ohm System

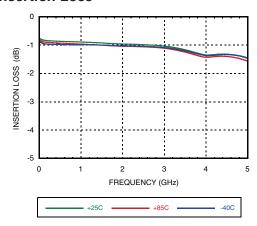
Parameter	Frequency	Min.	Тур.	Max.	Units
Insertion Loss	DC - 1.0 GHz DC - 2.0 GHz DC - 3.0 GHz DC - 4.0 GHz		0.8 0.9 1.2 1.8	1.1 1.2 1.5 2.1	dB dB dB dB
Isolation (RFC to RF1/RF2)	DC - 1.0 GHz DC - 2.0 GHz DC - 3.0 GHz DC - 4.0 GHz	60 54 45 42	70 57 50 47		dB dB dB dB
Return Loss (On State)	DC - 1.0 GHz DC - 2.0 GHz DC - 3.0 GHz DC - 4.0 GHz		23 22 20 18		dB dB dB dB
Return Loss (Off State)	0.5 - 2.0 GHz 0.5 - 3.0 GHz 0.5 - 4.0 GHz		22 17 14		dB dB dB
Input Power for 1 dB Compression	0.25 - 4.0 GHz	30	34		dBm
Input Third Order Intercept (Two-Tone Input Power = +10 dBm Each Tone)	0.25 - 1.0 GHz 1.0 - 2.0 GHz 2.0 - 3.0 GHz 3.0 - 4.0 GHz		53 54 53 52		dBm dBm dBm dBm
Switching Speed	DC - 4.0 GHz				
tRISE, tFALL (10/90% RF) tON, tOFF (50% CTL to 10/90% RF)			60 160		ns ns



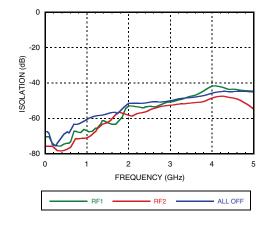


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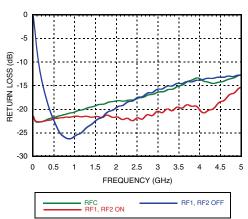
Insertion Loss



Isolation Between Ports RFC and RF1 / RF2

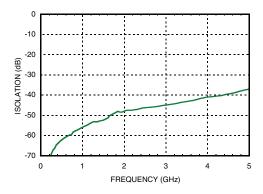


Return Loss

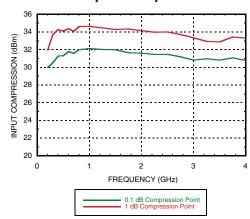


Note: RFC is reflective in "all off" state.

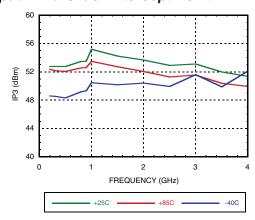
Isolation Between Ports RF1 and RF2



0.1 and 1 dB Input Compression Point



Input Third Order Intercept Point







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Absolute Maximum Ratings

	•
RF Input Power (Vctl = 0V/+5V) (0.25 - 4 GHz)	
Through Path Termination Path	33.6 dBm 26.5 dBm
Supply Voltage Range (Vdd)	+7 Vdc
Control Voltage Range (Vctl)	-1V to Vdd +1V
Hot Switch Power Level (Vdd = +5V)	+30 dBm
Channel Temperature	150 °C
Continuous Pdiss (T = 85 °C) (derate 17.6 mW/°C for through path, 8.6 mW/°C for temination path above 85 °C)	0.969 W
Termination Path	0.451 W
Thermal Resistance	
Through Path	67.1 °C/W
Termination Path	144.2 °C/W
Storage Temperature	-65 to +150 °C
Operating Temperature	-40 to +85 °C
ESD Sensitivity (HBM)	Class 1A

Bias Voltage & Current

Vdd Range = +5.0 Vdc ± 10%		
Vdd (Vdc)	Idd (Typ.) (mA)	ldd (Max.) (mA)
+5.0	1.2	3.5

TTL/CMOS Control Voltages

State	Bias Condition	
Low 0 to +0.8 Vdc @ <1 μA Typical		
High	+2.0 to +5.0 Vdc @ 40 μA Typical	

Truth Table

Control Input		Signal Path State		
Vctl	EN	RFC - RF1	RFC - RF2	
Low	Low	OFF	ON	
High	Low	ON	OFF	
Low	High	OFF	OFF	
High	High	OFF	OFF	

Note: DC blocking capacitors are required at ports RFC, RF1 and RF2. Their value will determine the lowest transmission frequency.

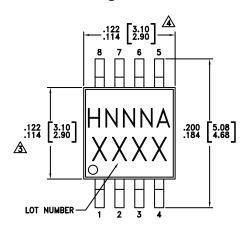


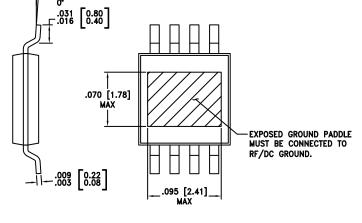


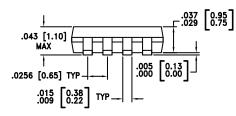


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Outline Drawing







NOTES:

- 1. LEADFRAME MATERIAL: COPPER ALLOY
- 2. DIMENSIONS ARE IN INCHES [MILLIMETERS]
- DIMENSION DOES NOT INCLUDE MOLDFLASH OF 0.15mm PER SIDE.
- A DIMENSION DOES NOT INCLUDE MOLDFLASH OF 0.25mm PER SIDE.
- ALL GROUND LEADS AND GROUND PADDLE MUST BE SOLDERED TO PCB RF GROUND.

Package Information

Part Number	Package Body Material	Lead Finish	MSL Rating	Package Marking [3]
HMC349AMS8G	Low Stress Injection Molded Plastic	Sn/Pb Solder	MSL1 [1]	H349A XXXX
HMC349AMS8GE	RoHS-compliant Low Stress Injection Molded Plastic	100% matte Sn	MSL1 [2]	<u>H349A</u> XXXX

^[1] Max peak reflow temperature of 235 °C

^[2] Max peak reflow temperature of 260 °C

^{[3] 4-}Digit lot number XXXX





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Pin Descriptions

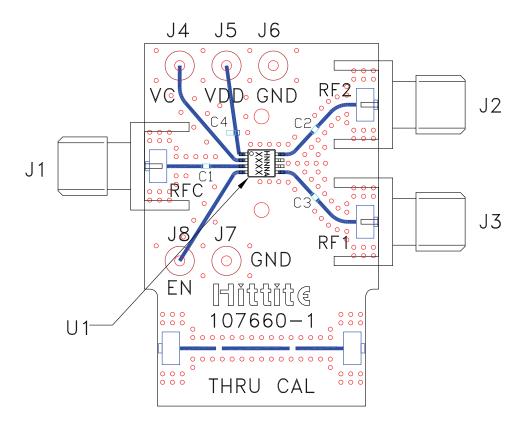
Pin Number	Function	Description	Interface Schematic
1	Vdd	Supply Voltage.	
2	Vctl	Control input. See truth and control voltage tables.	Vetl 134K =
3, 5, 8	RFC, RF1, RF2	These pins are DC coupled and matched to 50 Ohms. Blocking capacitors are required.	
4	EN	Enable. See truth and control voltage tables.	Vetl 134K =
6, 7	GND	Package bottom must also be connected to PCB RF ground.	○ GND =





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Evaluation PCB



List of Materials for Evaluation PCB 107662 - HMC349AMS8G [1]

Item	Description	
J1 - J3	PCB Mount SMA RF Connector	
J4 - J8	DC Pin	
C1 - C3	100 pF Capacitor, 0402 Pkg.	
U1	HMC349AMS8G / 349AMS8GE SPDT Switch	
PCB [2]	107660 Evaluation PCB	

^[1] Reference this number when ordering complete evaluation PCB

The circuit board used in the application should be generated with proper RF circuit design techniques. Signal lines at the RF port should have 50 Ohm impedance and the package ground leads and backside ground slug should be connected directly to the ground plane similar to that shown above. The evaluation circuit board shown above is available from Hittite Microwave Corporation upon request.

^[2] Circuit Board Material: Rogers 4350